

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B350AF	B360AF	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	50	60	V
Working Peak Reverse Voltage	$V_{RWM}$			
DC Blocking Voltage	$V_{RM}$			
Average Rectified Output Current	$I_O$	3		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	80		A

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJA</sub>	90	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R <sub>θJC</sub>	50	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V <sub>F</sub>	—	0.55 0.52	0.65 —	V	I <sub>F</sub> = 3A, T <sub>J</sub> = +25°C I <sub>F</sub> = 3A, T <sub>J</sub> = +125°C
Leakage Current (Note 6)	I <sub>R</sub>	—	0.02 0.03 24	0.2 0.2 —	mA	V <sub>R</sub> = 50V, T <sub>J</sub> = +25°C V <sub>R</sub> = 60V, T <sub>J</sub> = +25°C V <sub>R</sub> = 60V, T <sub>J</sub> = +125°C
Typical Capacitance	C <sub>T</sub>	—	110	—	pF	V <sub>R</sub> = 4.0V, f = 1MHz

Notes: 5. Device mounted on FR-4 substrate, 0.4"\*0.5", 2oz, single-sided, PC boards with 0.2"\*0.25" copper pad.  
6. Short duration pulse test used to minimize self-heating effect.

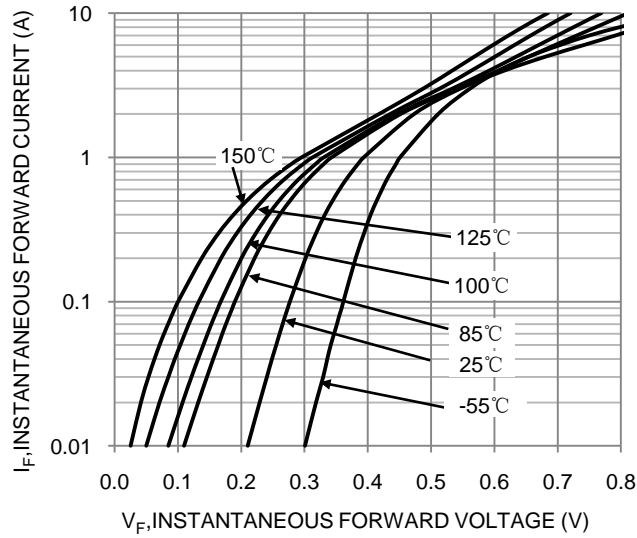


Figure 1. Typical Forward Characteristics

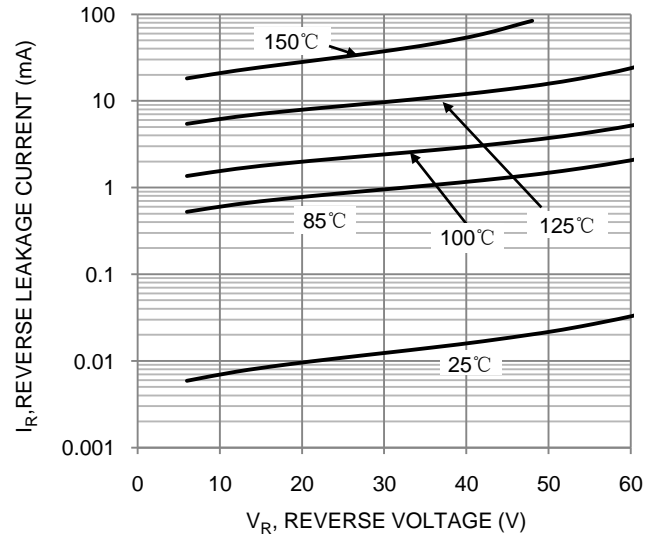


Figure 2. Typical Reverse Characteristics

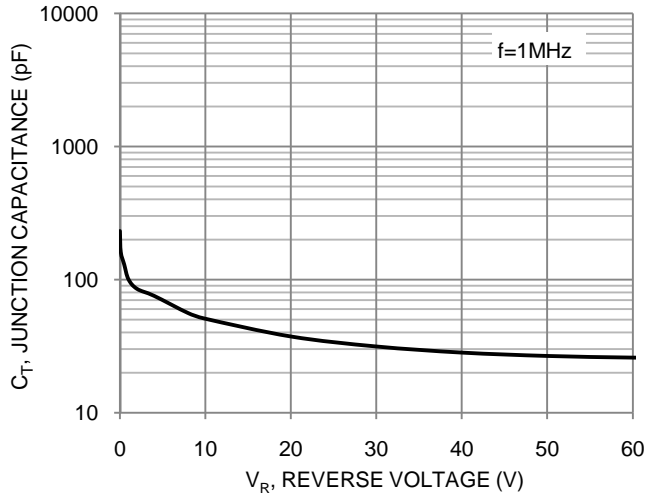


Figure 3. Typical Junction Capacitance

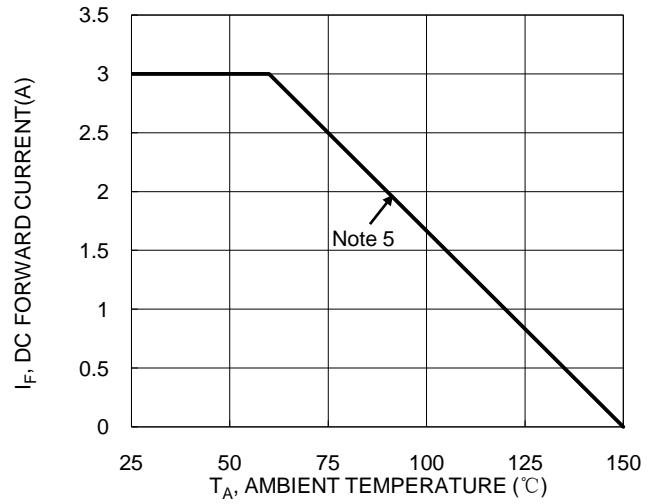
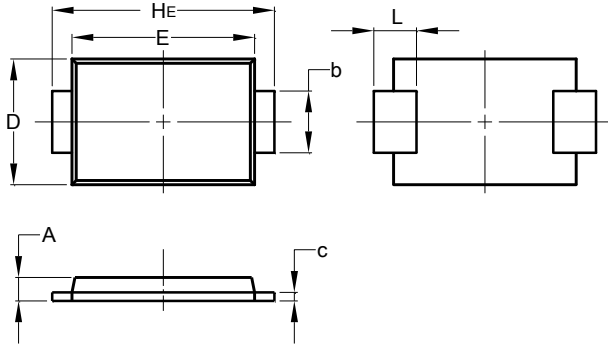


Figure 4. DC Forward Current Derating

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF

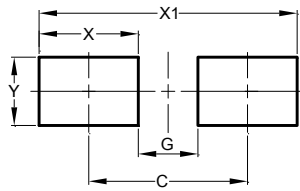


SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
HE	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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